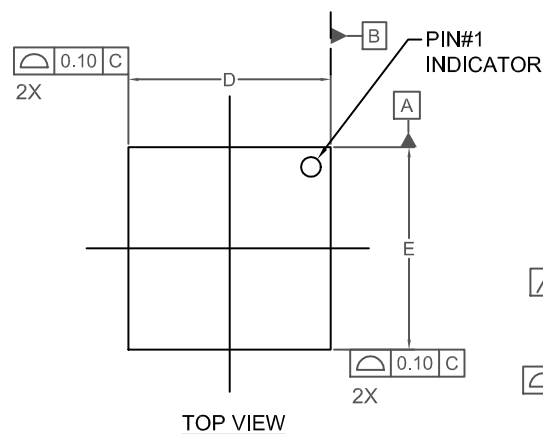


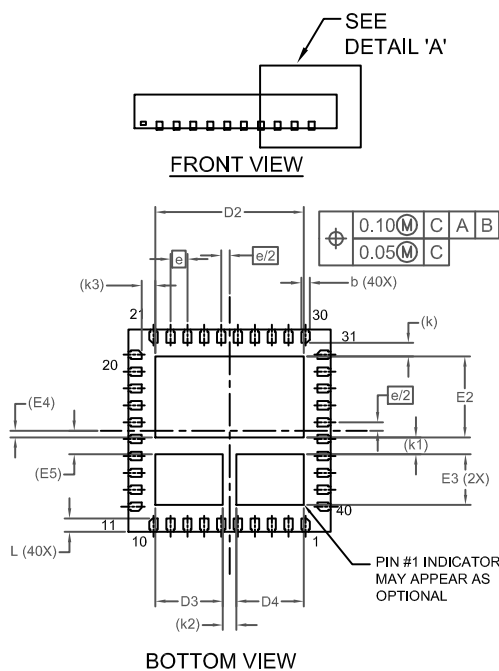
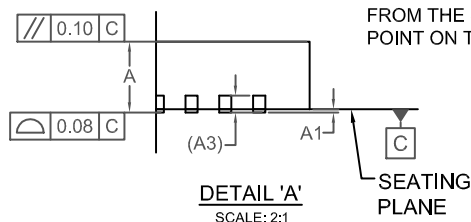
PQFN40 6X6, 0.5P
CASE 483AN
ISSUE A

DATE 08 JUN 2021

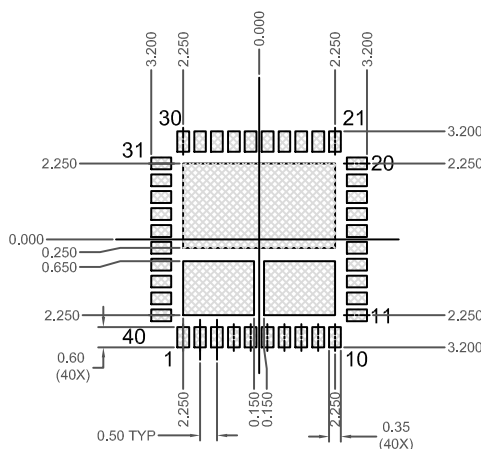


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.00	-	0.05
A3	0.25 REF		
b	0.20	0.25	0.30
D	5.90	6.00	6.10
D2	4.30	4.40	4.50
D3	1.90	2.00	2.10
D4	1.90	2.00	2.10
E	5.90	6.00	6.10
E2	2.30	2.40	2.50
E3	1.40	1.50	1.60
E4	0.20 REF		
E5	0.70 REF		
e	0.50 BSC		
e/2	0.25 BSC		
k	0.40 REF		
k1	0.50 REF		
k2	0.40 REF		
k3	0.40 REF		
L	0.30	0.40	0.50



LAND PATTERN RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL. SOLDERRM/D.

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